

### ABSTRACT OF THE DISCLOSURE

The present invention provides a semiconductor device whose reliability is improved by improving the adhesion strength of a metal plate or connecting chip, said plurality of electrodes and a lead frame with a molding resin. Further, the semiconductor device of the present invention prevents flow out of a conductive joining material to be employed for joining a lead terminal and the metal plate other than the joining range of the metal plate and the lead terminal, and mounts the metal plate at high precision. In a semiconductor device (a plastic package) in which a source electrode of a semiconductor chip and source terminal of a lead frame are electrically connected by a copper plate and sealed by a resin, the surface of the copper plate is roughened to improve the adhesion strength to a molding resin. Further, a stepped part is formed in the source terminal to prevent a conductive paste from flowing out. The structure is so formed as to fit claw parts in the lead frame.